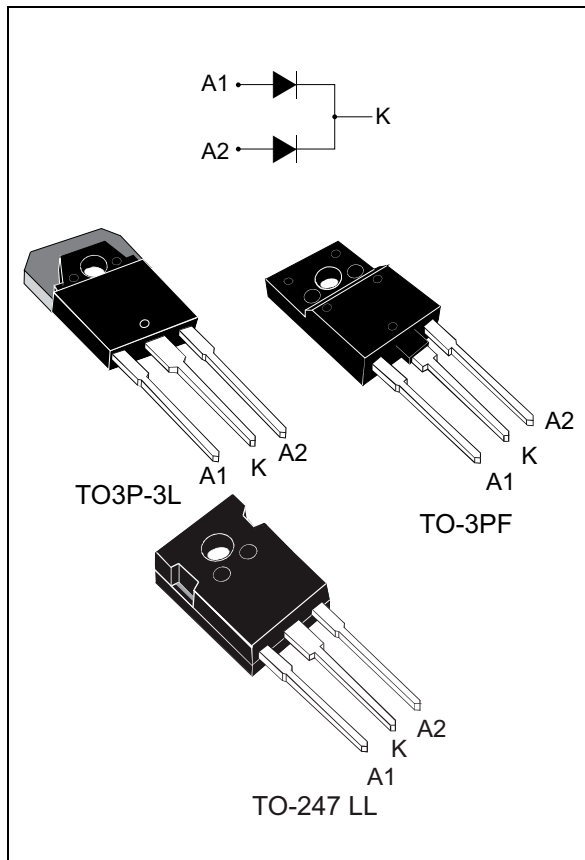


## Turbo 2 ultrafast high voltage rectifier

Datasheet – production data



### Description

The STTH30AC06C uses ST Turbo 2 600 V technology. It is suited as boost diode specially for use in air conditioning equipment as continuous mode interleaved power factor correction.

Table 1. Device summary

Symbol	Value
$I_{F(AV)}$	2 x 15A
$V_{RRM}$	600 V
$t_{rr}$ (typ)	40 ns
$V_F$ (typ)	1.15 V
$T_j$	175 °C

### Features

- Ultrafast switching
- Low reverse current
- Low thermal resistance
- Reduces switching and conduction losses
- Insulated package TO-3PF:
  - Insulated voltage: 2500 V<sub>DC</sub>

# 1 Characteristics

**Table 2. Absolute ratings (limiting values per diode at 25 °C, unless otherwise specified)**

Symbol	Parameter		Value	Unit
$V_{RRM}$	Repetitive peak reverse voltage		600	V
$I_{F(RMS)}$	Forward rms current		30	A
$I_{F(AV)}$	Average forward current	Per diode	15	A
		Per device	30	
$I_{FSM}$	Surge non repetitive forward current	$t_p = 10$ ms sinusoidal	140	A
$T_{stg}$	Storage temperature range		-65 to +175	°C
$T_j$	Maximum operating junction temperature		175	°C

**Table 3. Thermal parameters**

Symbol	Parameter		Value	Unit
$R_{th(j-c)}$	Junction to case (TO3P-3L, TO247 LL)	Per diode	1.5	°C/W
		Total	0.85	
$R_{th(c)}$	Coupling (TO3P-3L, TO247 LL)		0.2	
$R_{th(j-c)}$	Junction to case (TO-3PF)	Per diode	3.5	
		Total	2.7	
$R_{th(c)}$	Coupling (TO-3PF)		1.9	

**Table 4. Static electrical characteristics (per diode)**

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25$ °C	$V_R = V_{RRM}$	-		10	µA
		$T_j = 150$ °C		-	40	400	
$V_F^{(2)}$	Forward voltage drop	$T_j = 25$ °C	$I_F = 15$ A	-		1.95	V
		$T_j = 150$ °C		-	1.15	1.45	
		$T_j = 25$ °C	$I_F = 30$ A	-		2.25	
		$T_j = 150$ °C		-	1.42	1.8	

1. Pulse test:  $t_p = 5$  ms,  $\delta < 2\%$
2. Pulse test:  $t_p = 380$  µs,  $\delta < 2\%$

To evaluate the conduction losses use the following equation:

$$P = 1.1 \times I_{F(AV)} + 0.023 I_{F(RMS)}^2$$

Table 5. Dynamic characteristics (per diode)

Symbol	Parameter	Test conditions			Min.	Typ.	Max.	Unit
$t_{rr}$	Reverse recovery time	$T_j = 25\text{ }^\circ\text{C}$	$I_F = 0.5\text{ A}, I_{rr} = 0.25\text{ A}, I_R = 1\text{ A}$	-		30	ns	
			$I_F = 1\text{ A}, V_R = 30\text{ V}, dI_F/dt = 50\text{ A}/\mu\text{s}$	-	40	55		
$I_{RM}$	Reverse recovery current	$T_j = 125\text{ }^\circ\text{C}$	$I_F = 15\text{ A}, V_R = 400\text{ V}, dI_F/dt = 100\text{ A}/\mu\text{s}$	-	4	5.5	A	
$t_{fr}$	Forward recovery time	$T_j = 25\text{ }^\circ\text{C}$	$I_F = 15\text{ A}, V_{FR} = 1.9\text{ V}, dI_F/dt = +100\text{ A}/\mu\text{s}$	-		100	ns	
$V_{FP}$	Forward recovery voltage			-	2.5		V	

Figure 1. Average forward power dissipation versus average forward current (per diode)

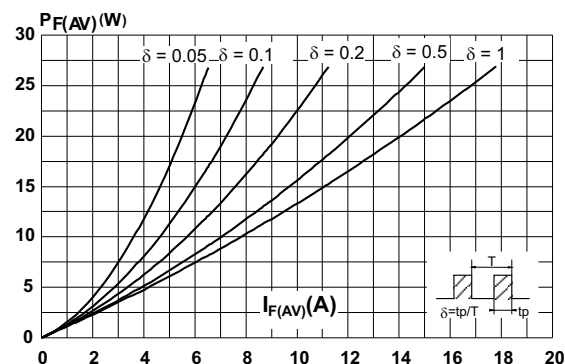


Figure 2. Forward voltage drop versus forward current (typical values, per diode)

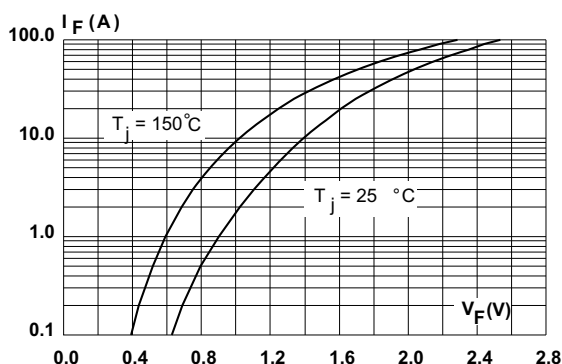


Figure 3. Forward voltage drop versus forward current (maximum values, per diode)

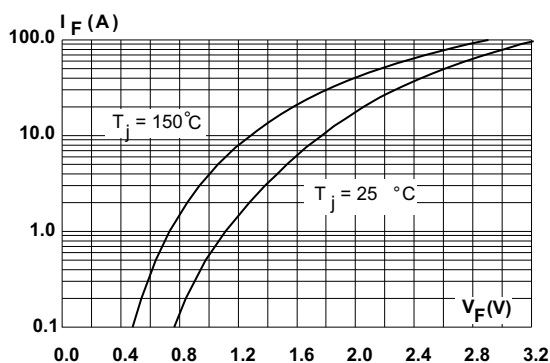


Figure 4. Relative variation of thermal impedance, junction to case, versus pulse duration (TO3P-3L, TO247 LL)

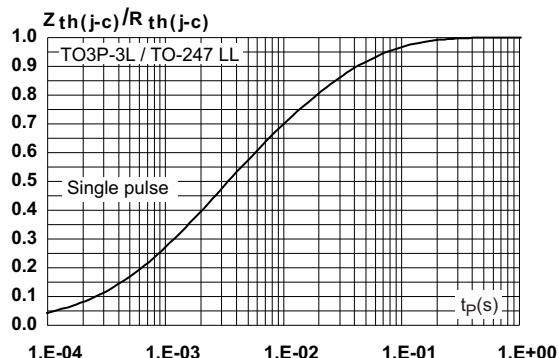


Figure 5. Relative variation of thermal impedance, junction to case, versus pulse duration (TO-3PF)

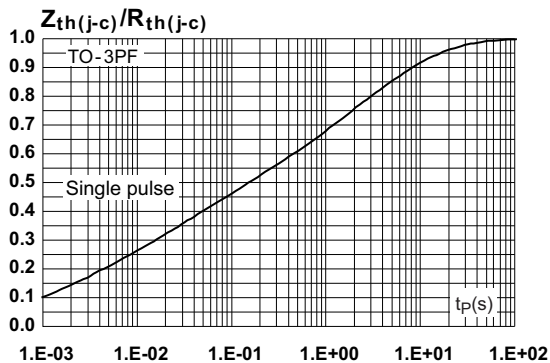


Figure 6. Peak reverse recovery current versus  $di_F/dt$  (typical values, per diode)

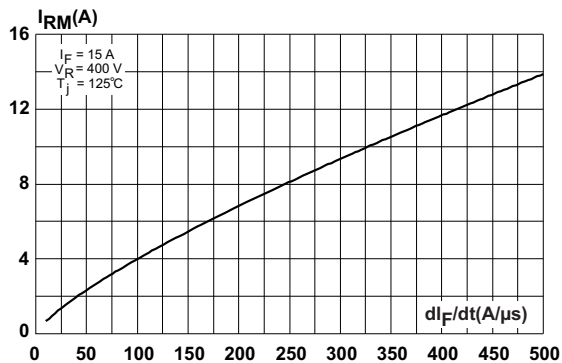


Figure 7. Reverse recovery time versus  $di_F/dt$  (typical values, per diode)

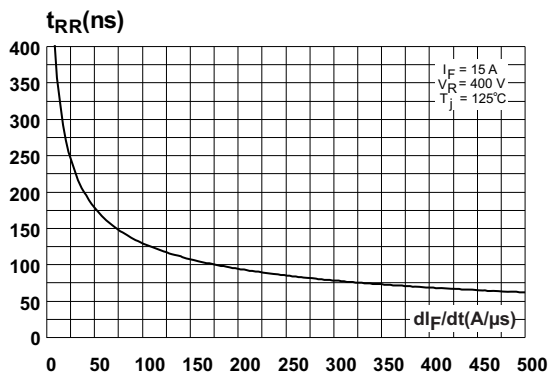


Figure 8. Reverse recovery charges versus  $di_F/dt$  (typical values, per diode)

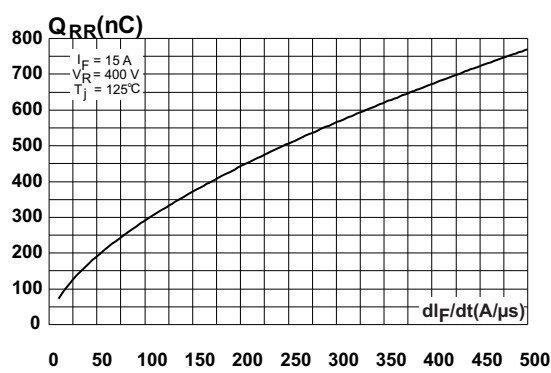


Figure 9. Reverse recovery softness factor versus  $di_F/dt$  (typical values, per diode)

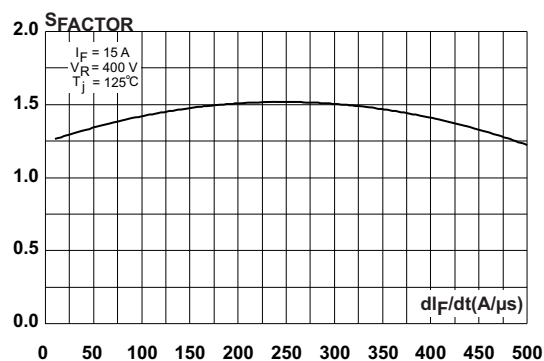
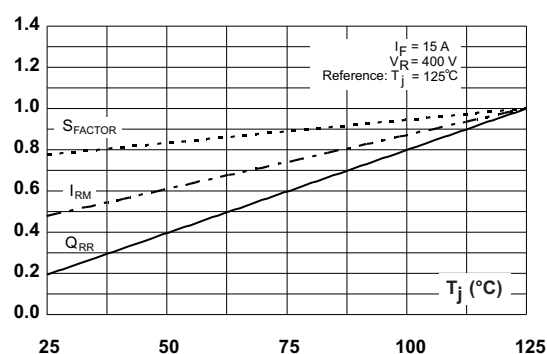
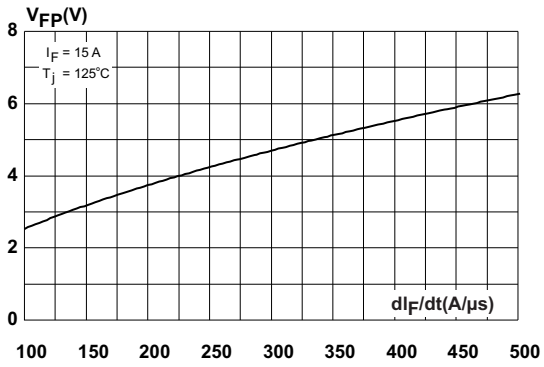


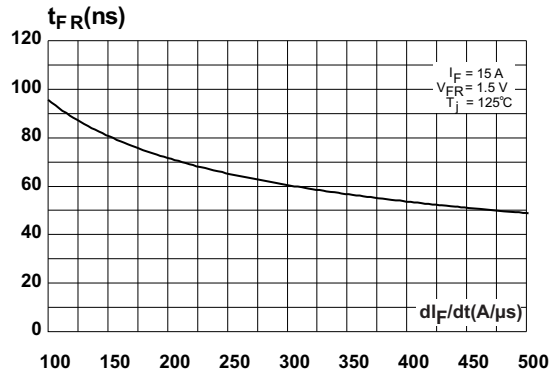
Figure 10. Relative variations of dynamic parameters versus junction temperature



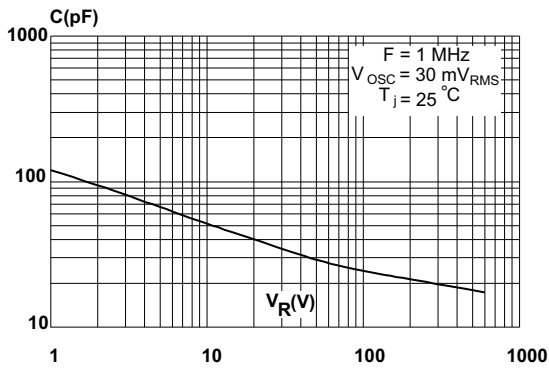
**Figure 11. Transient peak forward voltage versus  $di_F/dt$  (typical values, per diode)**



**Figure 12. Forward recovery time versus  $di_F/dt$  (typical values, per diode)**



**Figure 13. Junction capacitance versus reverse voltage applied (typical values, per diode)**



## 2 Package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)
- Recommended torque (TO-3PF): 0.4 to 0.6 N·m
- Maximum torque value (TO-247 LL): 1.0 N·m

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

### 2.1 TO3P-3L package information

Figure 14. TO3P-3L package outline

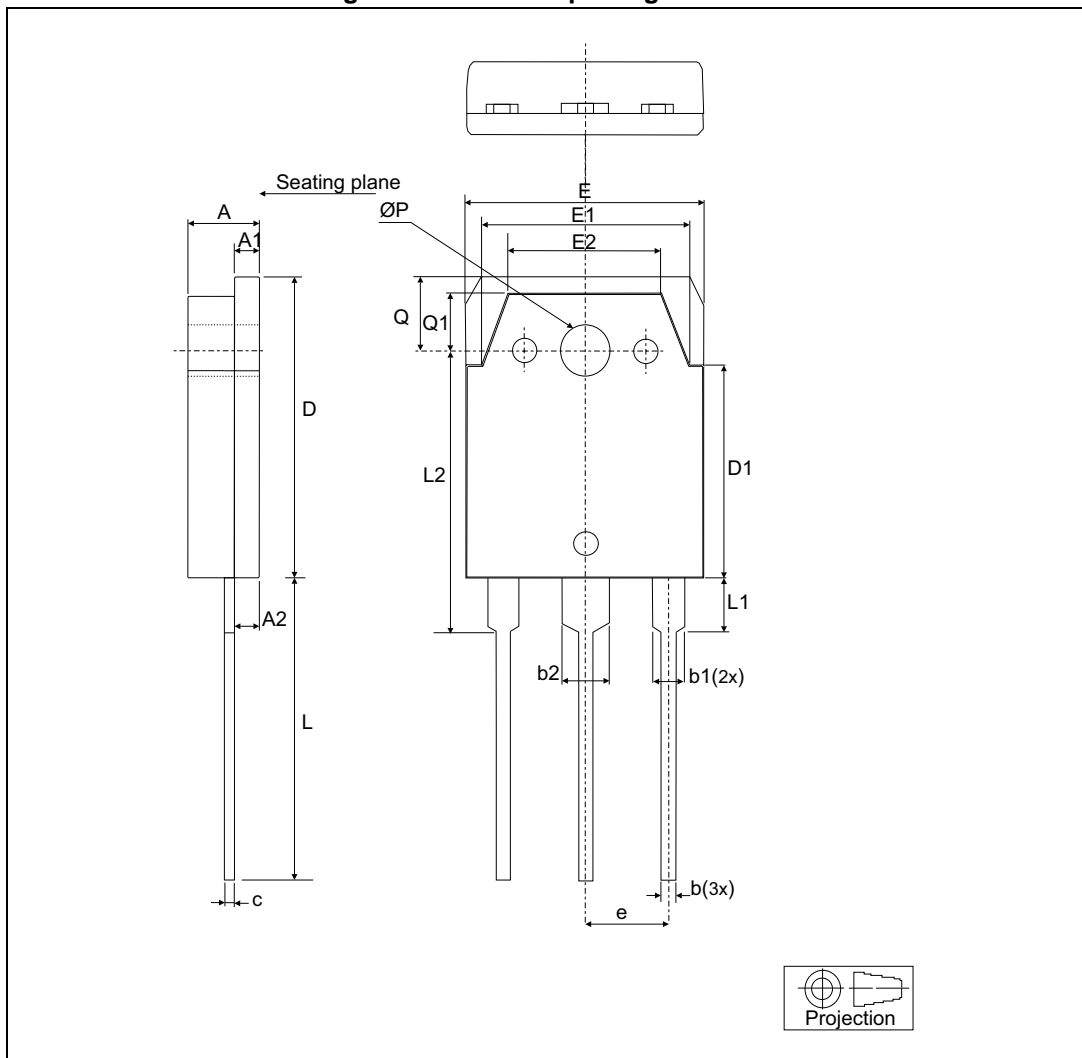


Table 6. TO3P-3L package mechanical data

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.6		5	0.18		0.19
A1	1.45	1.5	1.65	0.05	0.06	0.06
A2	1.20	1.40	1.60	0.04	0.05	0.06
b	0.80	1	1.20	0.03	0.04	0.05
b1	1.80		2.20	0.07		0.08
b2	2.80		3.20	0.11		0.12
c	0.55	0.60	0.75	0.02	0.02	0.03
D	19.70	19.90	20.10	0.77	0.78	0.79
D1		13.90			0.54	
E	15.40		15.80	0.60		0.62
E1		13.60			0.53	
E2		9.60			0.38	
e	5.15	5.45	5.75	0.20	0.21	0.22
L	19.50	20	20.50	0.76	0.78	0.80
L1		3.50			0.14	
L2	18.20	18.40	18.60	0.71	0.72	0.73
ØP	3.10		3.30	0.12		0.13
Q		5			0.19	
Q1		3.80			0.15	

## 2.2 TO-3PF package information

Figure 15. TO-3PF package outline

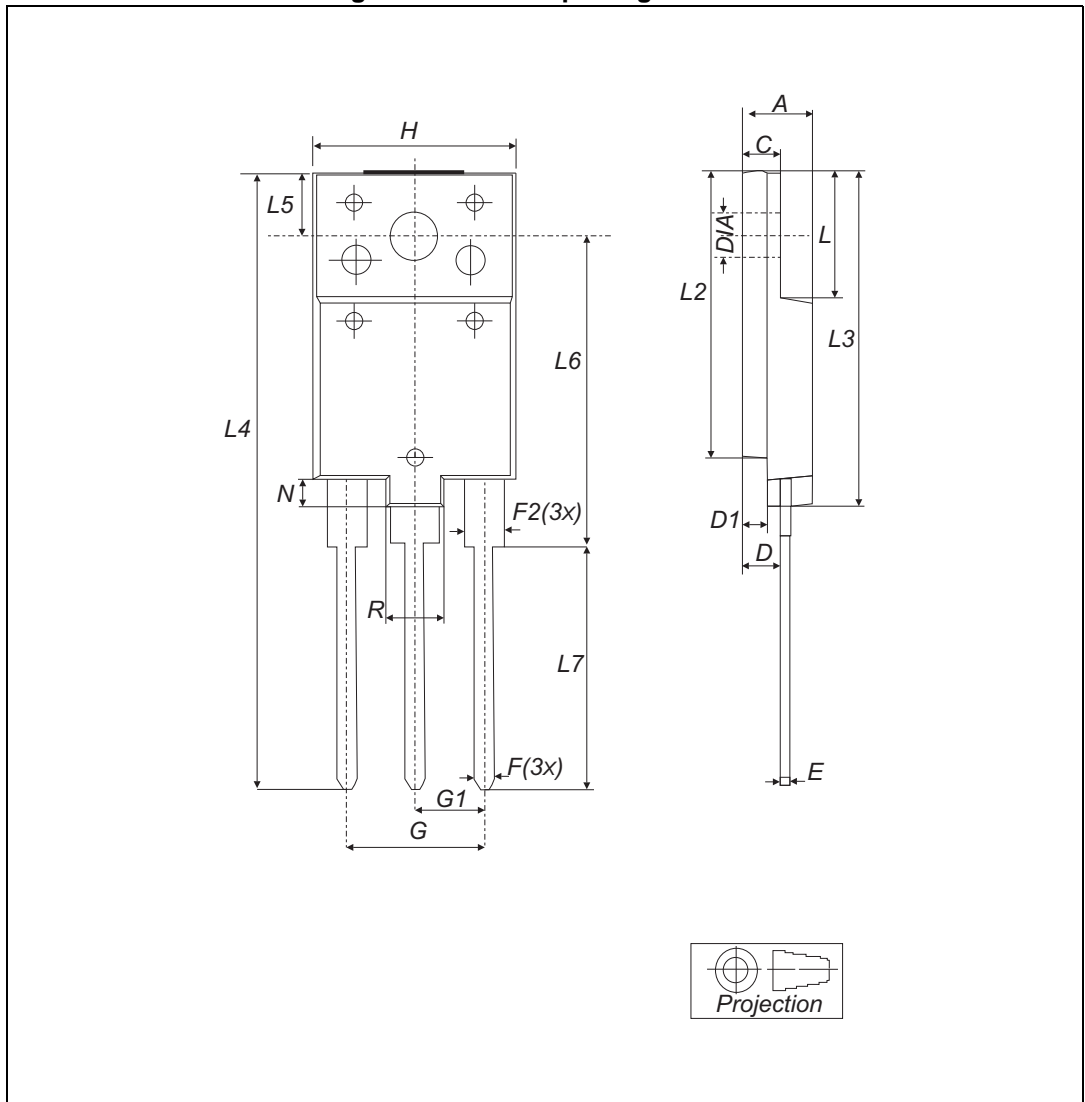




Table 7. TO-3PF mechanical data

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	5.30		5.70	0.2		0.22
C	2.80		3.20	0.11		0.12
D	3.10		3.50	0.12		0.13
D1	1.80		2.20	0.07		0.08
E	0.80		1.10	0.03		0.04
F	0.65		0.95	0.025		0.037
F2	1.80		2.20	0.07		0.08
G	10.30		11.50	0.40		0.45
G1		5.45			0.21	
H	15.30		15.70	0.60		0.61
L	9.80	10	10.20	0.38	0.39	0.40
L2	22.80		23.20	0.89		0.91
L3	26.30		26.70	1.03		1.05
L4	43.20		44.40	1.70		1.74
L5	4.30		4.70	0.16		1.18
L6	24.30		24.70	0.95		0.97
L7	14.60		15	0.57		0.59
N	1.80		2.20	0.07		0.08
R	3.80		4.20	0.14		0.16
Dia	3.40		3.80	0.13		0.15

### 2.3 TO-247 LL package information

Figure 16. TO-247 LL package outline

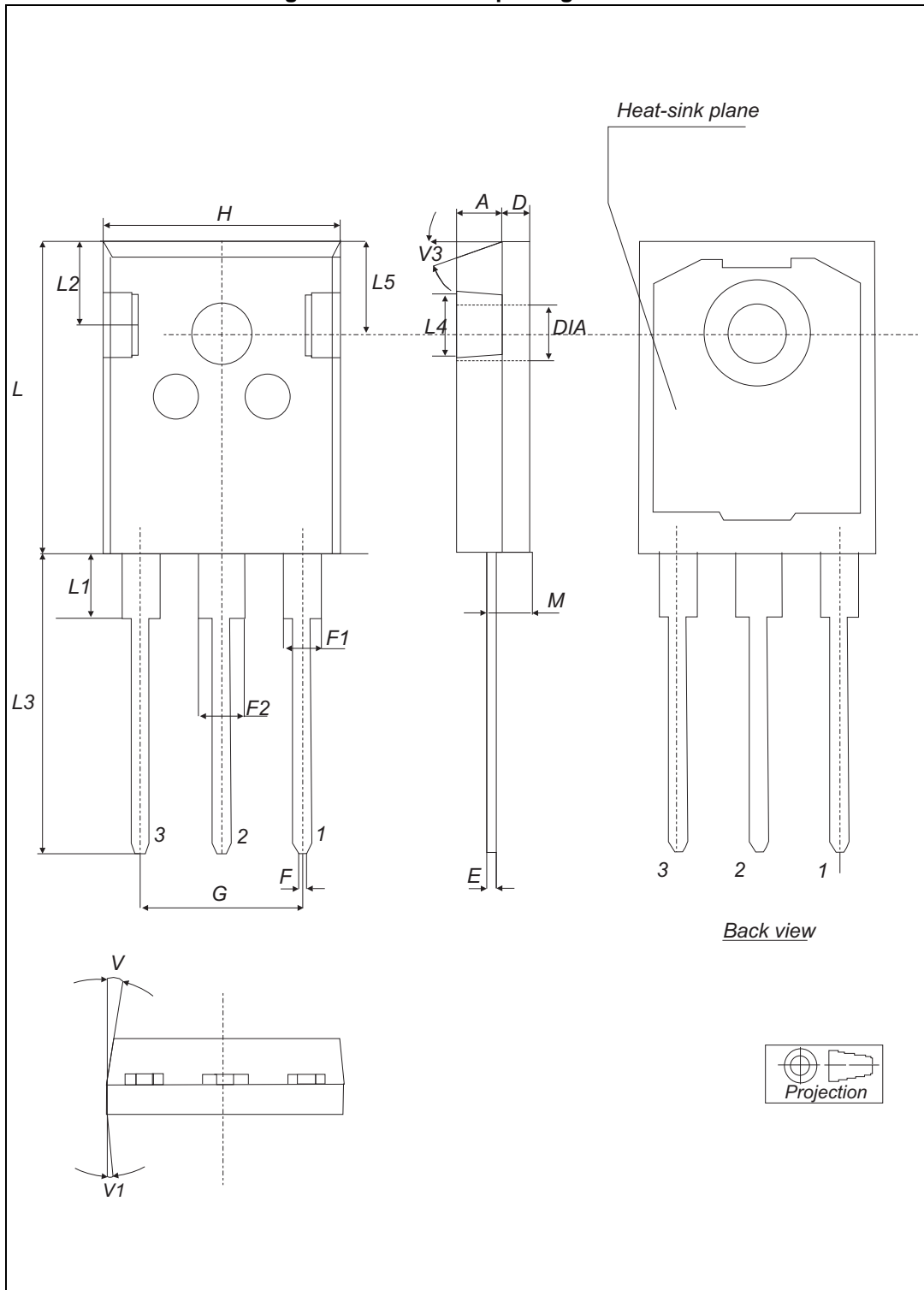


Table 8. TO-247 LL mechanical data

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ	Max.
A	4.90		5.15	0.192		0.202
D	1.85		2.10	0.072		0.082
E	0.55		0.67	0.021		0.026
F	1.07		1.32	0.042		0.051
F1	1.90		2.38	0.074		0.093
F2	2.87		3.38	0.11		0.133
G	10.90 BSC			0.429 BSC		
H	15.77		16.02	0.62		0.63
L	20.82		21.07	0.81		0.82
L1	4.16		4.47	0.163		0.175
L2	5.49		5.74	0.216		0.225
L3	20.05		20.30	0.789		0.799
L4	3.68		3.93	0.144		0.154
L5	6.04		6.29	0.237		0.247
M	2.25		2.55	0.088		0.10
V		10°			10°	
V1		3°			3°	
V3		20°			20°	
∅	3.55		3.66	0.139		0.143

### 3 Ordering information

**Table 9. Ordering information**

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STTH30AC06CP	STTH30AC06CP	TO3P-3L	5.26	30	Tube
STTH30AC06CPF	TH30AC06C	TO-3PF	5.6	30	Tube
STTH30AC06CWL	STTH30AC06CWL	TO-247 LL	4.36	30	Tube

### 4 Revision history

**Table 10. Document revision history**

Date	Revision	Changes
13-Nov-2013	1	First release.
25-Jun-2015	2	Update of cover page and <a href="#">Table 7</a> . Format updated to current standard.
01-Jul-2015	3	Updated <a href="#">Features</a> .

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